

# **Product Compliance Declaration**

Please see <a href="https://www.molex.com">www.molex.com</a> for the most up-to-date information.

**Contact Information** 

Name Molex Product Compliance E-Mail Product.Compliance@molex.com

**Part Information** 

Part Number 0022041091 Part Weight 0.903G

Part Name KK2.5 Wafer Assy W/Lock 9Ckt

# **Product Composition**

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)	
KK2.5 Wafer Assy W/Lock 9Ckt	Assembly		100	0.903	
WAFER	Component		50.1661	0.453	
PA66-FR(30)	Material		50.1661	0.453	
PA66	Substance		43.2683	0.390713	
Flame Retardant, ISO 1043-4 FR(30)	Substance		4.0133	0.03624	
Further Additives, not to declare	Substance	system	0.5017	0.00453	
Pigment portion, not to declare	Substance	system	0.3762	0.003398	
Antimonytrioxide	Substance	1309-64-4	2.0066	0.01812	
SQ WIRE PIN .025	Assembly		49.8339	0.45	
.025SQ WIRE PIN,PLAIN	Component		48.8372	0.441	
Cartridge Brass 70% Unplated	Material		48.8372	0.441	
Copper	Substance	7440-50-8	34.186	0.3087	
Zinc (metal)	Substance	7440-66-6	14.6512	0.1323	

#### Form Rev - F

Limitation of this Product Compliance Declaration: This declaration is based on the state of knowledge and belief of Molex as of the date that it is provided. Molex bases its knowledge and belief on information provided by numerous sources, including third parties, and in certain circumstances laboratory test results. Molex has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and substances. Molex represents that to the best of its knowledge that the information provided in this declaration is accurate. Molex's sole liability shall be to either replace the product or refund the purchase price of the product if it does not meet the requirement of this declaration.

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Tin Plating	Material		0.6176	0.005577
Tin	Substance	7440-31-5	0.6176	0.005577
Copper Plating	Material		0.379	0.003423
Copper	Substance	7440-50-8	0.379	0.003423

### **ROHS Declaration Information**

Regulatory Revision EU 2015/863

Compliance Status Compliant

**Contained Substances Exceeding Threshold** 

None

**Exemptions** 

None

# **REACH-SVHC Declaration Information**

**Regulatory Revision** D(2022)4187-DC (10 June 2022)

**Contained Substances Exceeding Threshold** 

None

### **GADSL Declaration Information**

Regulatory Revision GADSL imported from IMDS

# **Contained Substances Exceeding Threshold**

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Lead	Cartridge Brass 70% (CA260)	*Note	350	Yes
Lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	500	Yes
Antimonytrioxide	PA66-FR(30)	*Note	50,000	Yes

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Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Copper	Cartridge Brass 70% (CA260)	*Note	700,000	Yes
Copper	e-plate Cu (electrodeposited Copper Coatings)	*Note	999,625	Yes

<sup>\*</sup>Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

## **Exemptions**

Part Name	Exemption
Cartridge Brass 70% (CA260)	44 Concentration within acceptable GADSL limits
e-plate Sn (electrodeposited Tin Coatings, bright and matt)	44 Concentration within acceptable GADSL limits

# **HFLH Declaration Information**

Regulatory Revision IEC 61249-2-21

# **Contained Substances Exceeding Threshold**

None

#### **China ROHS Declaration Information**

Part Number 0022041091							
Part Name KK2.5 Wafer Assy W/Lock 9Ckt	(e)						
Part Information			Haz	zardous S	Substance	s	
Components		Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
KK2.5 Wafer Assy W/Lock 9Ckt		0	0	0	0	0	0
WAFER		0	0	0	0	0	0
SQ WIRE PIN .025		0	0	0	0	0	0
.025SQ WIRE PIN,PLAIN		0	0	0	0	0	0

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## **Additional Information**

Annex XVII to REACH (76/769/EEC)	Compliant
Regulation (EU) 2019/1021 (POP)	Compliant

#### **Process Information**

Component Plating / Surface Finish	N/A
Termination Base Alloy	N/A
Solder Alloy	N/A
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

Aug 19, 2022